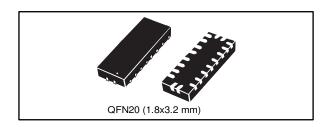
STP4CMP



Low voltage 4-channel constant current LED driver with charge pump

Datasheet - production data



Features

- Operating voltage range: V_{CC} 2.7 V to 5.5 V
- Full RGB function support
- 4-channel LED driver with individual ON/OFF control directly from input pins
- Individually programmable output current for the 4 channels through 4 external resistors with a max. capability of 30 mA
- Absolute output current accuracy of max. ±7% and channel-to-channel mismatch of max. ±4%
- Selectable charge pump enable/disable
- Thermal protection
- Small QFN20 (1.8x3.2 mm) package

Applications

- · Mobile phone display backlighting
- RGB LED indicator driver

Description

The STP4CMP is a charge-pump-based 4channel LED driver designed for RGB illumination or LCD display backlighting. The STP4CMP works off a battery with an input voltage between 2.7 V and 5.5 V. The device generates regulated current sinks with high absolute and channel-to-channel accuracy to drive up to 4 LEDs. It can support LEDs with forward voltage as high as 3.8 V. The current sink for each channel can be set with 4 individual external resistors. Each channel is controlled independently. The PWM control can be applied directly to the 4 EN (enable) pins to provide brightness control. When enabled, the charge pump, which uses a small ceramic bucket capacitor between C_{1P} and C_{1N}, operates to regulate the V_{OUT} with a clamping voltage at typ. 5 V. The tiny QFN20 (1.8x3.2 mm) package allows the device to be also used for applications with space limitations.

Table 1: Device summary

Oder code	Package	Packing
STP4CMPQTR	QFN20 (1.8x3.2 mm)	Tape and reel

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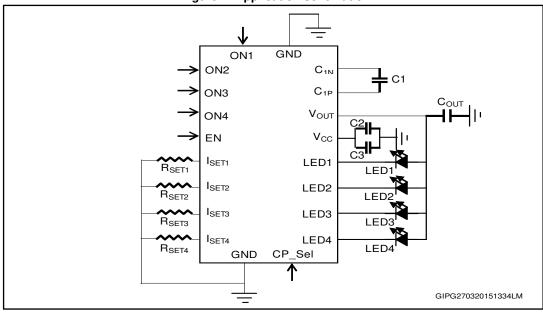


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1 Application schematic

Figure 1: Application schematic



The above figure shows the typical application diagram with the external components. To ensure an optimal charge pump performance, it is highly recommended that the bucket capacitor, C_{1} , and the output capacitor, C_{OUT} , to be placed as close as possible to the pins.

Table 2: Typical external components

Component	Manufacturer	Part number	Value	Size	
0.0	Murata	GRM155R61A105KE15D	1 [/10 \/	0400	
C ₁ ,C _{OUT}	TDK	C1005X5R1A105MT	1 μF/10 V	0402	
C2	Murata	GRM188R60J106ME84	10 [/6 0 \/	0603	
02	TDK	C1608X5R0J106MT	10 μF/6.3 V	0603	
C3	Murata	GRM155R60J104KA01D	100 5	0400	
C3	TDK	C1005X5R1C104KT	100 nF	0402	
R _{SET1-4} ⁽¹⁾	Tyco	CPF0402B976RE1	976 Ω	0402	
LED1-4 (2)					

Notes:

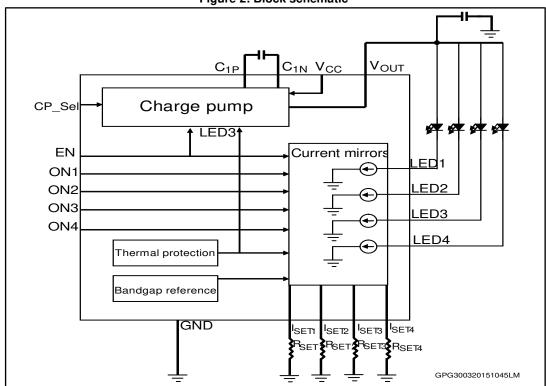
 $[\]ensuremath{^{(2)}}\mbox{Forward}$ voltage typ. 3.8 V.



All the above components refer to a typical application. Operation of the device is not limited to the choice of these external components.

 $^{^{(1)}649~\}Omega$ to 7.87 k Ω according to the desired output current from each channel.

Figure 2: Block schematic



STP4CMP Pin configuration

2 Pin configuration

Figure 3: Pin connections (top view)

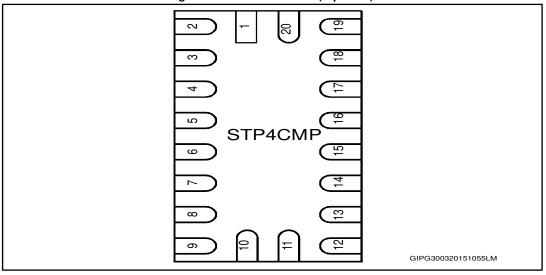


Table 3: Pin description

Pin	Symbol	Description	
1	ON1	LED1 enable	
2	ON2	LED2 enable	
3	ON3	LED3 enable	
4	ON4	LED4 enable	
5	EN	Chip enable	
6	I _{SET1}	LED1 max. current setting resistor	
7	I _{SET2}	LED2 max. current setting resistor	
8	I _{SET3}	LED3 max. current setting resistor	
9	I _{SET4}	LED4 max. current setting resistor	
10	GND	Ground	
11	CP_SEL	Charge pump mode selection, 1 = enable 0 = disable	
12	LED4	4 th LED current sink	
13	LED3	3 rd LED current sink	
14	LED2	2 nd LED current sink	
15	LED1	1 st LED current sink	
16	V_{CC}	Supply voltage	
17	V_{OUT}	Charge pump output	
18	C _{1P}	Positive terminal of charge pump bucket capacitor	
19	C _{1N}	Negative terminal of charge pump bucket capacitor	
20	GND	Ground	

Maximum ratings STP4CMP

3 Maximum ratings

Table 4: Absolute maximum ratings

Symbol	Parameter	Value	Unit
ON ₁₋₄ , V _{CC} , EN, CP_SEL, C _{1P} , C _{1N}	Supply voltage	- 0.3 to + 6.0	V
VOUT	Output voltage	- 0.3 to + 6.0	V
LED1-4, I _{SET1-4}	Current setting	-0.3 to 2	V
ESD	Human body model	±1500	
	Charged device model	±500	V
	Machine model	±200	
T _{AMB}	Operating ambient temperature	- 30 to 85	°C
TJ	Maximum operating junction temperature	+150	°C
T _{STG}	Storage temperature	-65 to 150	°C

Table 5: Recommended operating conditions

Symbol	Parameter	Min.	Тур.	Max.	Unit
V _{CC}	Supply voltage	2.7		5.5	V
T _{op}	Operating temperature	-40		85	°C
I _{LED}	Current through each LED	2.5		30	mA
T _{pwm} _ON	ON time of PWM signal at each ON pin	00			
T _{pwm} _OFF	OFF time of PWM signal at each ON pin	33			μs
V_{fw}	LED forward voltage			3.8	V

Table 6: Thermal data

Symbol	Parameter	Value	Unit
R _{thJA} ⁽¹⁾	Thermal resistance junction-ambient	70	°C/W

Notes:

⁽¹⁾This parameter corresponds to the PCB board, 4-layer with 1 inch² of cooling area.

4 Electrical characteristics

 $V_{CC}=3.3~V,~V_{EN}=V_{ON1}=V_{ON2}=V_{ON3}=V_{ON4}=V_{CC},~V_{CP_SEL}=V_{CC},~R_{SET1}=R_{SET2}=R_{SET3}=R_{SET4}=649~\Omega,~C_1=1~\mu\text{F},~typical~values~are~at~T_A=25~^{\circ}\text{C}~unless~otherwise~specified}.$

Table 7: Electrical characteristics

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{CC}	Supply voltage		2.7		5.5	٧
V	Charge pump	$ 2.7 \text{ V} \leq \text{V}_{\text{CC}} < 3.1 \text{ V}; $ $ \text{V}_{\text{CP_SEL}} = \text{V}_{\text{CC}}; \text{I}_{\text{OUT}} \leq 40 \text{ mA} $		5		٧
V_{cp_clamp}	clamp voltage	$V_{CC} > 3.1 \text{ V};$ $V_{CP_SEL} = V_{CC}; I_{OUT} \le 120 \text{ mA}$		5		
T _{cp_start}	Charge pump start- up time	From CP_SEL low to high transition to CP reaches steady-state 5 V			10	ms
ı	LED sink current for	R_{setx} = 649 Ω at V_{LEDx} = 0.9 V; V_{CC} > 3.1 V	27.9	30	32.1	mA
I _{LED1,2,3,4}	each channel	R_{setx} = 7.87 kΩ at V _{LEDx} = 0.9 V; $V_{\text{CC}} \ge 3.1$ V	2.33	2.5	2.68	mA
ΔI_LED	Output current error between each channel	$R_{SET1} = R_{SET2}, R_{SET3} = R_{SET4},$ $T_A = 25 ^{\circ}C$		±1	±4	%
V_{IH}	High level input voltage		2.0			V
V_{IL}	Low level input voltage				0.8	٧
	Supply operating current	$\begin{split} &V_{ON1} = V_{ON2} = V_{ON3} = V_{ON4} = GND;\\ &\text{no-load;}\\ &V_{CC} = 5.5 \text{ V (charge pump disabled); } &V_{CP_SEL} = GND,\\ &R_{SET1} = R_{SET2} = R_{SET3} = R_{SET4} = 7.87 \text{ k}\Omega \end{split}$		3.6		m A
lcc		$\begin{split} &V_{ON1} = V_{ON2} = V_{ON3} = V_{ON4} = GND;\\ &\text{no-load;}\\ &V_{CC} = 5.5 \text{ V (charge pump disabled); } &V_{CP_SEL} = GND,\\ &R_{SET1} = R_{SET2} = R_{SET3} = R_{SET4} = 649 \ \Omega \end{split}$		1.7		
icc		$\begin{split} &V_{ON1} = V_{ON2} = V_{ON3} = V_{ON4} = GND;\\ &\text{no-load;}\\ &V_{CC} = 3.3 \text{ V (charge pump enabled);}\\ &V_{CP_SEL} = V_{CC},\\ &R_{SET1} = R_{SET2} = R_{SET3} = R_{SET4} = 7.87 \text{ k}\Omega \end{split}$		4.5		ША
		$\begin{split} &V_{ON1} = V_{ON2} = V_{ON3} = V_{ON4} = GND;\\ &\text{no-load;}\\ &V_{CC} = 3.3 \text{ V (charge pump enabled);}\\ &V_{CP_SEL} = V_{CC},\\ &R_{SET1} = R_{SET2} = R_{SET3} = R_{SET4} = 649 \ \Omega \end{split}$		17.2		
I _{SHUTDOWN}	Supply current during power-down	$\begin{aligned} V_{EN} &= V_{ON1} = V_{ON2} = V_{EN} = V_{ON3} = V_{ON4} \\ &= V_{CP_SEL} = 0 \ V \end{aligned}$			5	μΑ



Electrical characteristics

STP4CMP

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
T_{SD}	Thermal shutdown			150		ô
T _{HS}	Thermal shutdown hysteresis			15		°C

STP4CMP Detailed description

5 Detailed description

The STP4CMP is a charge-pump-based 4-channel LED driver designed for RGB illumination or LCD display backlighting, using constant current topology. Each of the 4 channels can be controlled independently. When ONx is pulled high, a constant current is sunk into the LEDx pin when one LED is connected. This constant current is defined or programmed by the value of the resistor on the I_{SETX} pin.

5.1 Enable pin

The active high enable input pin is used to shut down the whole device. When this pin is pulled low, the device goes into shutdown mode with 5 μ A max. current consumption only. An internal pulled down of 300 k Ω is present on this pin.

5.2 LED turn-on pin (ONx)

When the EN pin is pulled high, the STP4CMP provides the flexibility to control ON/OFF on the 4 channels independently through the 4 active high ON pins. To control the brightness of each LED channel, it is possible to drive the selected ON pin with a PWM signal with a frequency up to min. 33 μs $T_{\text{ON}}/T_{\text{OFF}}.$ An internal pull-down of 300 $k\Omega$ is present on these pins.

5.3 Programmable output current

The LED currents on the 4 channels are programmed individually through a resistor connected from I_{SET1} , I_{SET2} , I_{SET3} , I_{SET4} to ground. The relationship between the resistor (R_{SFT}) and the LED current (I_{LFD}) is given by the below equation:

 $R_{SET} = 16x(1.22/I_{LED})$

5.4 Charge pump

The STP4CMP charge pump can be disabled or enabled according to the CP_SEL pin. When enabled (CP_SEL is high), the charge pump provides a clamping voltage of typ. 5.0 V to ensure enough headroom to drive the LEDs. An internal pull-down of 300 k Ω is present on this pin. The charge pump can be disabled by pulling low the CP_SEL pin, based on the V_{CC} and forward voltage of the LEDs used. This allows the connection of V_{CC} directly to V_{OUT} to drive the external LEDs. At V_{CC} 3.1 V, the charge pump maintains regulation at 5 V when the total current drawn from it (on V_{OUT} pin) is \leq 120 mA. At 2.7 \leq V_{CC} < 3.1 V, in order for the charge pump to maintain regulation at 5 V, the total current drawn from it (on V_{OUT} pin) must be lowered to \leq 40 mA.

5.5 Thermal protection

The thermal protection circuit ensures the device shutdown when it is overheated (for example, due to an output short-circuit) to typ. 150 °C. The device resumes normal operation when the temperature drops by 15 °C from the thermal shutdown threshold.

6 Typical performance characteristics

Figure 4: Efficiency vs. V_{IN}, I_{OUT} = 10 mA

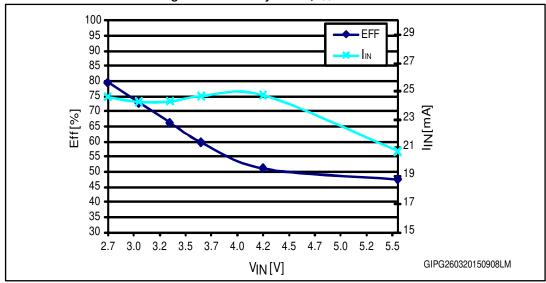
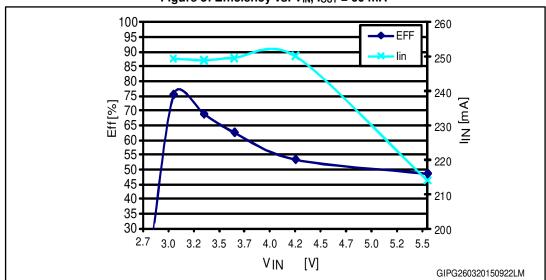


Figure 5: Efficiency vs. V_{IN}, I_{OUT} = 60 mA



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Figure 6: V_{OUT} vs. V_{IN}

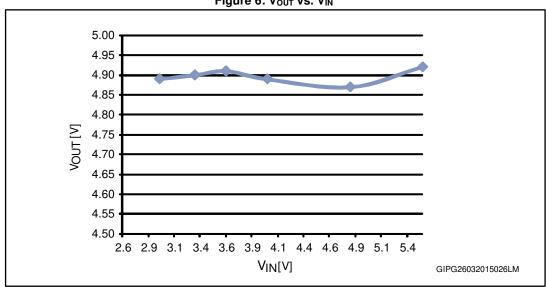


Figure 7: PWM modulation CH1-2

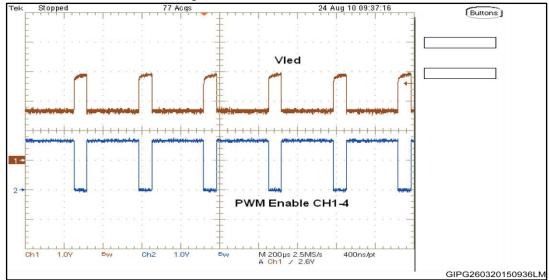
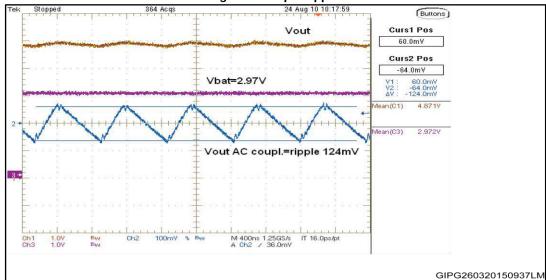


Figure 8: Output ripple



STP4CMP PCB layout

7 PCB layout

7.1 Recommended

The STP4CMP is a charge pump power device so it requires a proper PCB layout in order to obtain the necessary stability and optimize line/load regulation and output voltage ripple. Input, output, and boost capacitors must be as close as possible to their relative pins.

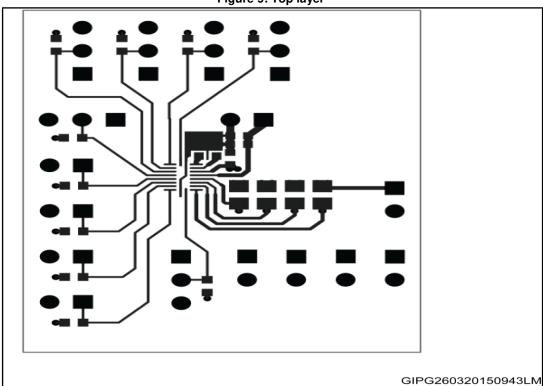


Figure 9: Top layer

PCB layout STP4CMP

Figure 10: Bottom layer

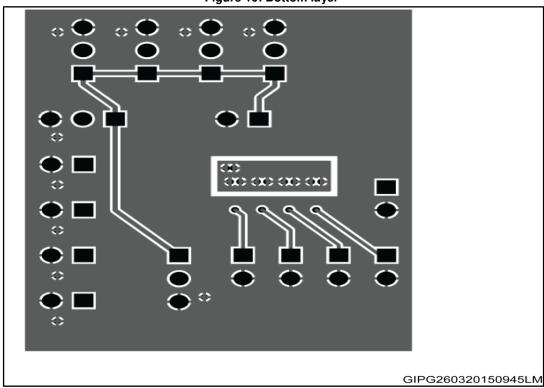
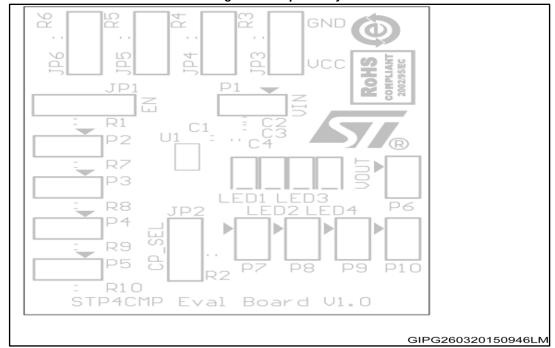


Figure 11: Top overlay



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STP4CMP PCB layout

7.2 Evaluation board

Figure 12: Evaluation board

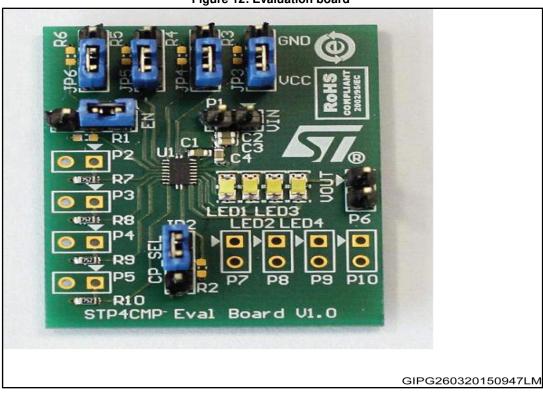
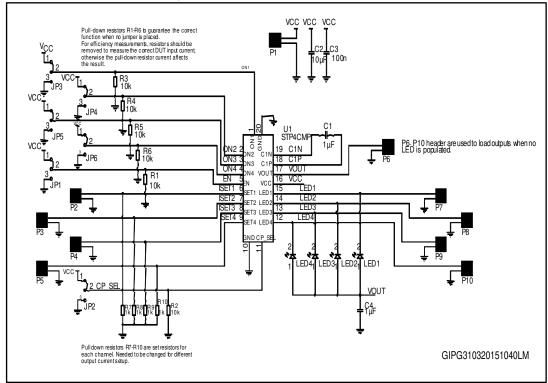


Figure 13: Evaluation board schematic



8 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

STP4CMP Package information

8.1 QFN20 (1.8x3.2 mm) package information

Figure 14: QFN20 (1.8x3.2 mm) package outline

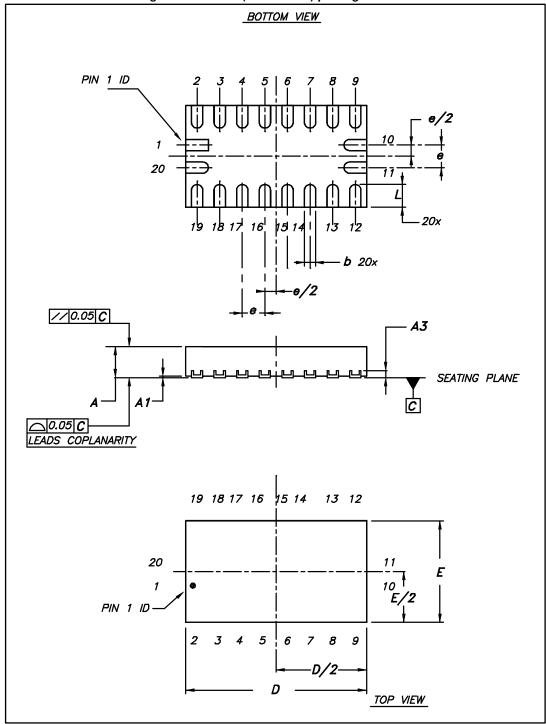
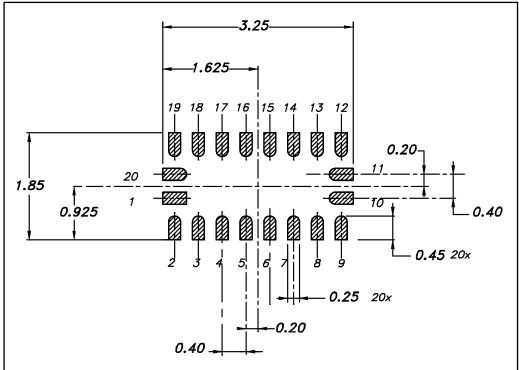


Table 8: QFN20 (1.8x3.2 mm) package mechanical data

table of the control					
Dim.		mm			
Dilli.	Min.	Тур.	Max.		
A	0.45	0.50	0.55		
A1	0	0.02	0.05		
A3		0.127			
b	0.15	0.20	0.25		
D	3.15	3.20	3.25		
Е	1.75	1.80	1.85		
е		0.40			
L	0.35	0.40	0.45		

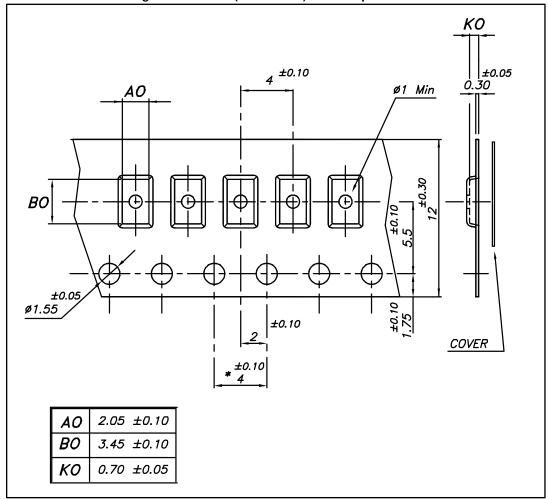
Figure 15: QFN20 (1.8x3.2 mm) recommended footprint



STP4CMP Package information

8.2 Packing information

Figure 16: QFN20 (1.8x3.2 mm) carrier tape outline



GIPG260320151015LM

Figure 17: QFN20 (1.8x3.2 mm) reel outline

Drawing is not in scale and dimensions are in mm

STP4CMP Revision history

9 Revision history

Table 9: Document revision history

Date	Revision	Changes
09-Jun-2009	1	Initial release.
24-Jan-2012	2	Document status promoted from preliminary data to datasheet. Added section 7.
09-Apr-2015	3	Updated features.

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